# National Semiconductor

# LH4009/LH4009C Fast Buffer

### **General Description**

The LH4009 is a very high speed, FET input, voltage follower/buffer designed to provide high current drive at frequencies from DC to over 190 MHz. The LH4009/LH4009C will provide  $\pm 200$  mA into  $50\Omega$  loads ( $\pm 250$  mA peak) at slew rates of 10000V/\mus. In addition, it exhibits excellent phase linearity.

The LH4009 is intended to fulfill a wide range of buffer applications. Due to its high speed it does not degrade the system performance. Its high output current makes it adequate for most loads. Only a single + 10V supply is needed for a 5 Vpp video signal. In addition, the LH4009 can continuously drive 50 $\Omega$  coaxial cables.

These devices are constructed using specially selected junction FETs and active laser trimming to achieve guaranteed performance specifications. The LH4009K is specified for operation from  $-55^{\circ}$ C to  $+125^{\circ}$ C; whereas, the LH4009CK is specified from  $-25^{\circ}$ C to  $+85^{\circ}$ C. LH4009K and LH4009CK are available in an 8-pin TO-3 package. LH4009CT is available in an 11-pin TO-220 package and is specified from  $-25^{\circ}$ C to  $+85^{\circ}$ C.

#### Features

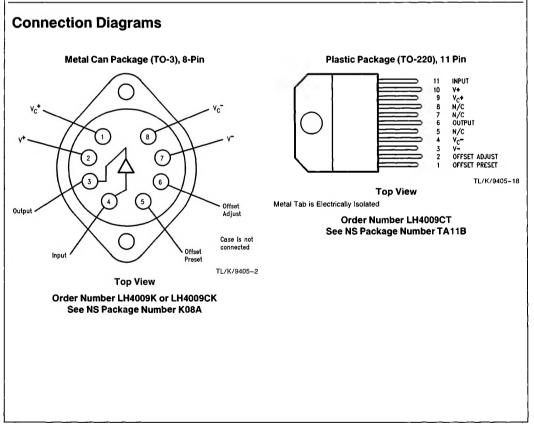
Fast	10000V/μs
Wide range single or dual supply operation	
Wide power bandwidth	DC to 150 MHz
High output drive	$\pm 10V$ with 50 $\Omega$ load
Low phase non-linearity	2 degrees
Fast rise times	2 ns
High input resistance	10 <sup>10</sup> Ω

Pin compatible with LH0063

Built in short circuit protection

#### Applications

- High speed line drivers
- Video impedance transformation
- Op amp isolation buffers
- Yoke driver for high resolution CRT
- High impedance input buffer



#### **Absolute Maximum Ratings**

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/Distributors for availability and specifications.

40V
ЗW
175°C
Equal to Supplies
± 200 mA

Peak Output Current	± 250 mA
Duration of Short Circuit Protection	30 sec
Operating Temperature Range	
LH4009	-55°C to +125°C
LH4009C	-25°C to +85°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature	
(Soldering, 10 sec.)	300°C
ESD	TBD

#### DC Electrical Characteristics V\_S = $\pm 15V$ , R<sub>S</sub> = R<sub>L</sub> = $50\Omega$ , T<sub>A</sub> = $25^{\circ}C$ unless otherwise specified

Symbol	Parameter	Conditions	LH4009			Units
			Typical	Tested Limit (Note 2)	Design Limit (Note 3)	(Max unless otherwise noted)
V <sub>OS</sub>	Output Offset	(Note 4)	10	25 <b>150</b>		mV
IB	Input Bias Current	(Note 4)	5	30 <b>100</b>		nA
Av	Voltage Gain	$V_{lN} = \pm 10V, R_L = 1 k\Omega$	0.92	0.9 <b>0.85</b>		V/V (Min)
Av	Voltage Gain	$V_{IN} = \pm 10V$	0.87	0.85 <b>0.8</b>		V/V (Min)
CIN	Input Capacitance		10			pF
ROUT	Output Impedance	$V_{OUT} = \pm 10V$		5		Ω
vo	Output Voltage Swing		±11	±10 ± <b>8</b>		V (Min)
LSVO	Low Supply Output Voltage Swing	$V_{S} = \pm 5.0V$		± 2.5		V (Min)
IS	Supply Current	$V_{S} = \pm 15V, R_{L} = \infty,$	47	60 <b>75</b>		mA
LVIS	Low Voltage Supply Current	$V_{S} = \pm 5.0V$	45	60		mA
PD	Power Consumption	$V_{S} = \pm 15V, R_{L} = \infty$	1.26	1.8		W
PD	Power Consumption	$V_{\rm S} = \pm 5.0 V, R_{\rm L} = \infty$		600		mW

#### **DC Electrical Characteristics** $V_S = \pm 15V$ , $R_S = R_L = 50\Omega$ , $T_A = 25^{\circ}C$ unless otherwise specified

Symbol	Parameter	Conditions	LH4009C			Units
			Typical	Tested Limit (Note 2)	Design Limit (Note 3)	(Max unless otherwise noted)
V <sub>OS</sub>	Output Offset	(Note 4)	10	50		mV
IB	Input Bias Current	(Note 4)	5	30		nA
Av	Voltage Gain	$V_{IN} = \pm 10V, R_L = 1 k\Omega$	0.92	0.9		V/V (Min)
Av	Voltage Gain	$V_{IN} = \pm 10V$	0.87	0.85		V/V (Min)
CIN	Input Capacitance					pF
ROUT	Output Impedance	$V_{OUT} = \pm 10V$		5		Ω
Vo	Output Voltage Swing		±11	±10		V (Min)
Vo	Output Voltage Swing	$V_{S} = \pm 5.0V$		±2.5		V (Min)
ls	Supply Current	$V_{S} = \pm 15V, R_{L} = \infty$	42	60		mA
LVIS	Low Voltage Supply Current	$V_{\rm S} = \pm 5.0 V$	45	60		mA
PD	Power Consumption	$V_S = \pm 15V, R_L = \infty$	1.26	1.8		w
PD	Power Consumption	$V_S = \pm 5.0V, R_1 = \infty$		600		mW

### AC Electrical Characteristics $T_J = 25^{\circ}C$ , $V_S = \pm 15V$ , $R_S = 50\Omega$ , $R_L = 50\Omega$

Symbol	Parameter	Conditions		Units		
			Typical	Tested Limit (Note 2)	Design Limit (Note 3)	(Max unles otherwise noted)
SR	Slew Rate Rising Edge	V <sub>IN</sub> = 20 V <sub>PP</sub> 20%-80%	11,000			V/µs (Min)
SR	Slew Rate Falling Edge	V <sub>IN</sub> = 20 V <sub>PP</sub> 20%-80%	8000			V∕µs (Min)
BW	Bandwidth	V <sub>IN</sub> = 1.0 Vrms	190	160		MHz (Min)
PBW	Power Bandwidth	V <sub>IN</sub> = 20 V <sub>PP</sub>	150	130		MHz (Min)
	Rise Time	$\Delta V_{IN} = 20 V_{PP}$	1.2			ns
	Propagation Delay	$\Delta V_{IN} = 20 V_{PP}$	1.3			ns

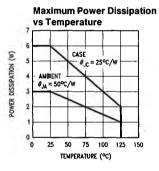
Note 1: Boldface limits are guaranteed over full temperature range. Operating ambient temperature range of LH4009C is -25°C to +85°C, and LH4009 is -55°C to + 125°C.

Note 2: Tested limits are guaranteed and 100% production tested.

Note 3: Design limits are guaranteed (but not production tested) over the indicated temperature or temperature range. These limits are not used to calculate outgoing quality level.

Note 4: Specifications are at 25°C junction temperature due to requirements of high speed automatic testing. Actual values at operating temperature will exceed value at T<sub>1</sub> = 25°C.

## **Typical Performance Characteristics**



**Input Bias Current** 

104

10n

10 INPUT

100p

10p -15 -10 -5 0 5

E

CURRENT 100

BIAS (

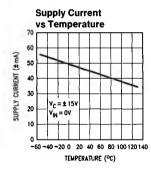
vs Input Bias Voltage

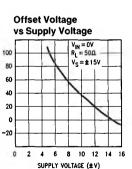
INPUT BIAS VOLTAGE (V)

V<sub>S</sub> = ± 15V

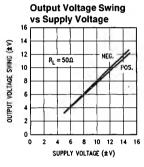
15

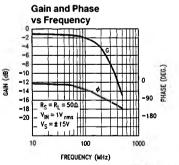
10





OFFSET VOLTAGE (mV)

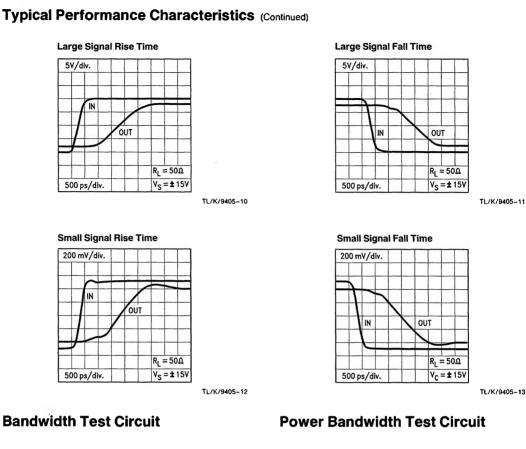


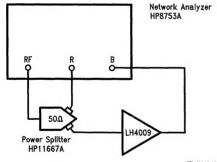


TL/K/9405-9

### Typical Performance Characteristics (Continued)







TL/K/9405-14

Network Analyzer HP8753A ATTENUATOR RF в 20 dB ö Ö 50Q Power Splitter HP11667A 1 GHz Power Amplifier Minicircuits No. ZHL -2 -8 TL/K/9405-15

### **Application Hints**

RECOMMENDED LAYOUT PRECAUTIONS: RF/video printed circuit board layout rules should be followed when using the LH4009 since it will provide power gain to frequencies over 200 MHz. Ground planes are recommended and power supplies should be decoupled at each device with low inductance capacitors. In addition, ground plane shielding may be extended to the metal case of the device since it is electrically isolated from internal circuitry. Alternatively, the case should be connected to the output to minimize input capacitance.

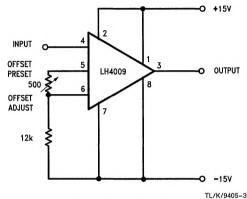


FIGURE 1. Offset Zero Adjust

SHORT CIRCUIT PROTECTION: The LH4009 features built-in short circuit protection. It will protect the device against output shorts to ground for up to 30 seconds. Beyond that the device may get degraded.

CAPACITIVE LOADING: The LH4009 is designed to drive capacitive loads such as coaxial cables in excess of several thousand picofarads without susceptibility to oscillation. However, peak current resulting from (C  $\times$  dV/dt), should

be limited below absolute maximum peak current ratings for the devices.

$$\left(\frac{\Delta V_{\text{IN}}}{\Delta t}\right) \times C_{\text{L}} \le I_{\text{OUT}} \le \pm 250 \text{ mA}$$

In addition, power dissipation resulting from driving capactive loads plus standby power should be kept below package power rating:

$$\begin{split} & P_{diss} \geq P_{DC} + P_{AC} \\ & _{pkg.} \\ & P_{diss} \geq (V^+ - V^-) \times I_S + P_{AC} \\ & _{pkg.} \\ & P_{AC} = (Vp\text{-}p)^2 \times f \times C_L \end{split}$$

f = frequency

C<sub>L</sub> = Load Capacitance

OPERATION WITHIN AN OP AMP LOOP: The device may be used as a current booster or isolation buffer within a closed loop with op amps such as LH0032, LM6161, or LM118. An isolation resistor of  $47\Omega$  should be used between the op amp output and the input of LH4009. The wide bandwidth and high slew rate of the LH4009 assures that the loop has the characteristics of the op amp and that additional rolloff is not required.

HARDWARE: In order to utilize the full drive capabilities of both devices, each should be mounted with a heat sink particularly for extended temperature operation. The cases of both are isolated from the circuit and may be connected to system chassis.

#### ATTENTION!

POWER SUPPLY BYPASSING is necessary to prevent oscillation in all circuits. Low inductance ceramic disc capacitance with the shortest practical lead lengths must be connected from each supply lead (within <1/4 to 1/2" of the device package) to a ground plane. Capacitors should be two 0.1  $\mu$ F ceramic and one 4.7  $\mu$ F solid tantalum capacitors in parallel on each supply lead.

